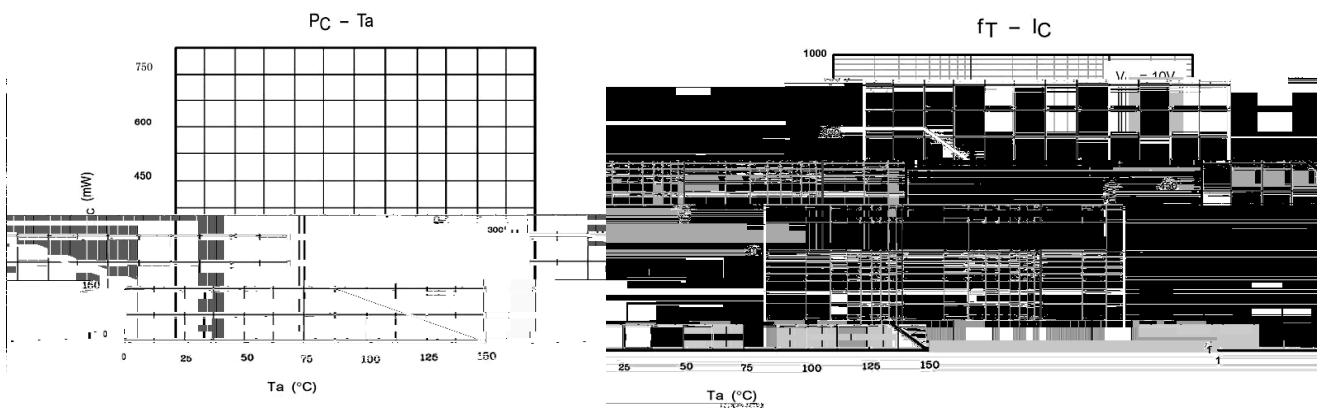
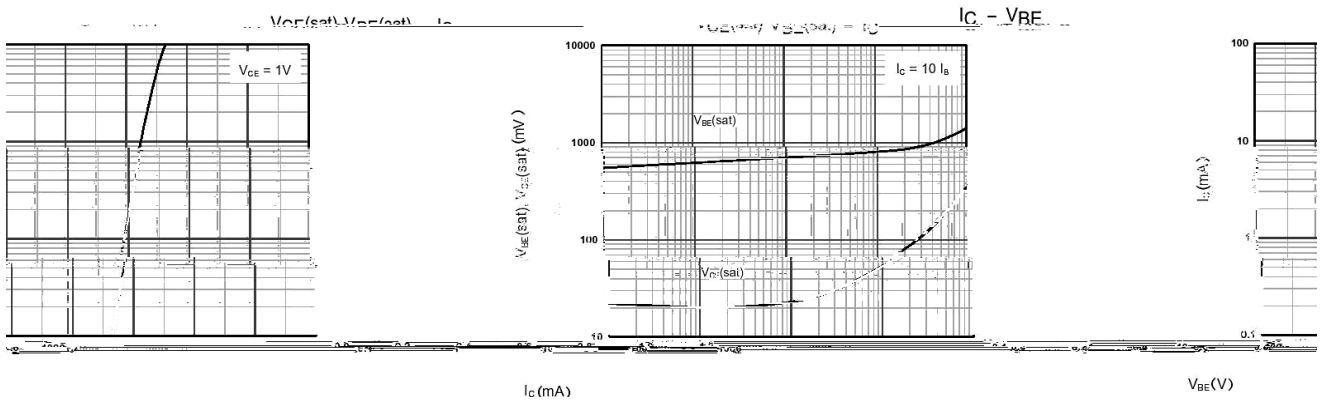
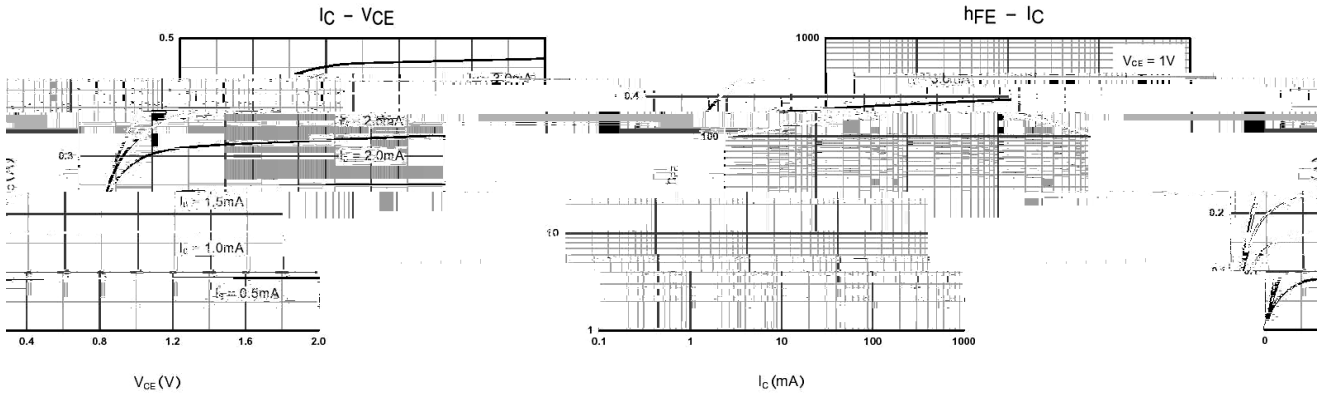




Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	40	V
Collector to Emitter Voltage	$V_{CEO}$	25	V
Emitter to Base Voltage	$V_{EBO}$	6.0	V
Collector Current	$I_C$	1.5	A
Base Current	$I_B$	0.5	A
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=0.1mA$ $I_E=0$	40			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=2.0mA$ $I_B=0$	25			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=0.1mA$ $I_C=0$	6.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=35V$ $I_E=0$			0.1	$\mu A$
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=6.0V$ $I_C=0$			0.1	$\mu A$
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0V$ $I_C=100mA$	85		300	
	$h_{FE(2)}$	$V_{CE}=1.0V$ $I_C=800mA$	40			

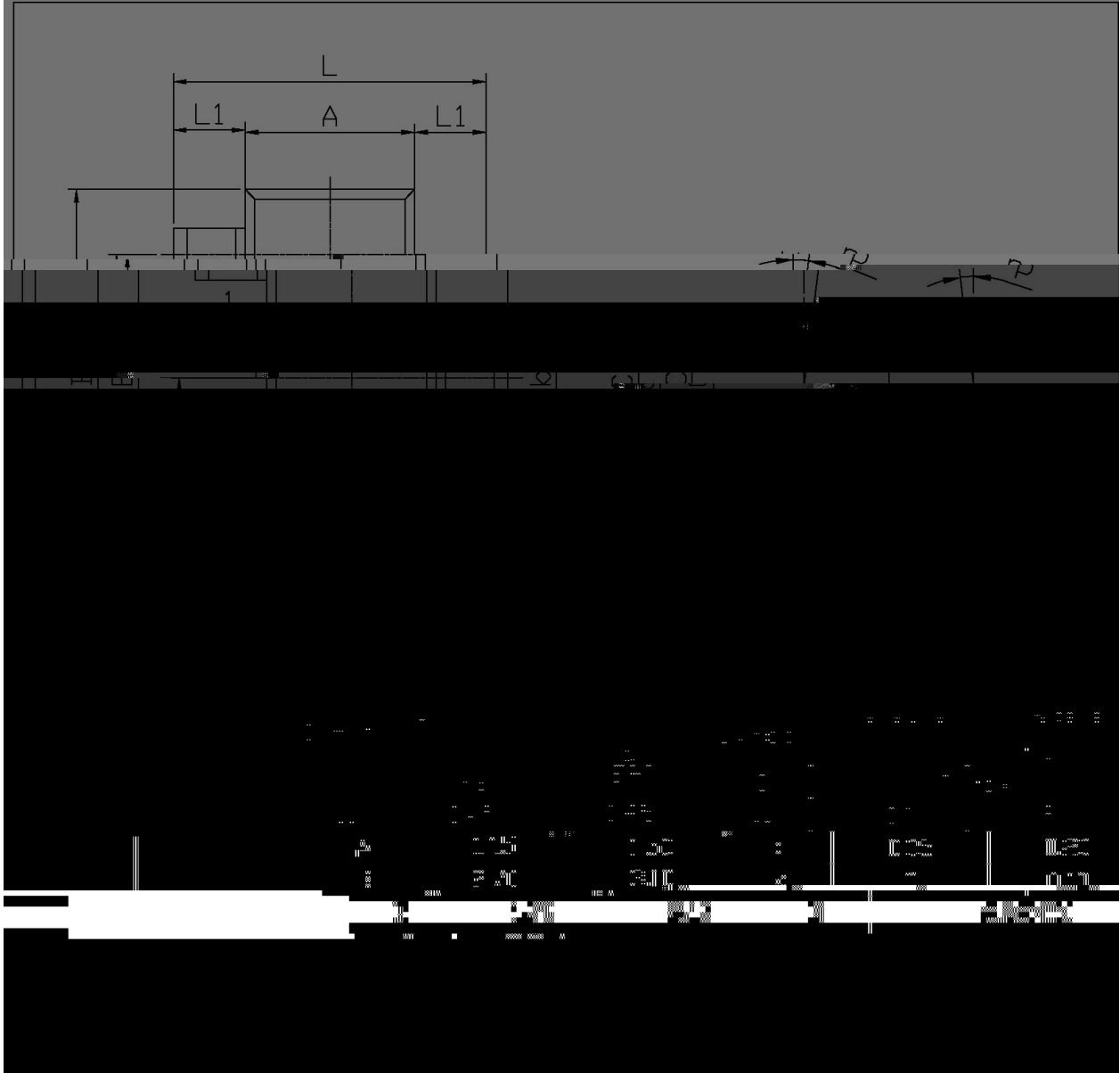
/ Electrical Characteristic Curve



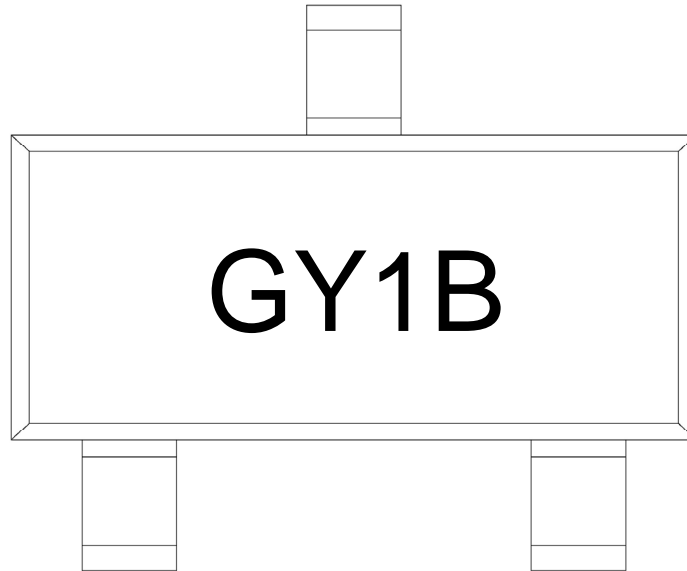
/ Package Dimensions

SOT-23

单位: mm



/ Marking Instructions



G

Y1

B             $h_{FE}$

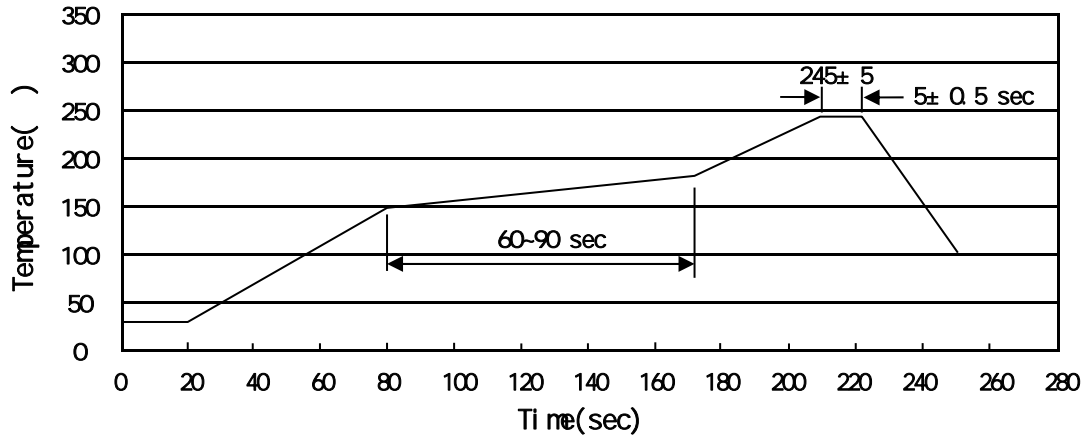
Note:

G            Halogen Free Product Code

Y1           Product Type Code

B             $h_{FE}$  Classifications Symbol Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |        |   |
|---|-------|-----|-------|--------|---|
| 1 | 150   | 180 | 60    | 90sec; | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;   | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10    | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
SOT-23	3,000	10	30,000	6	180,000	7 x8	180x120x180	390x385x205

/ Notices